

40V N-CHANNEL ENHANCEMENT MODE MOSFET PowerDI3333-8 (Type UX)

Product Summary

BV _{DSS}	R _{DS(ON)} Max	I _D Max T _C = +25°C
40V	$7.9 \text{m}\Omega$ @ $V_{GS} = 10V$	54.8A
	$12m\Omega @ V_{GS} = 4.5V$	44.5A

Features

- 100% Unclamped Inductive Switching-Ensures More Reliable and Robust End Application
- Low On-Resistance
- Low Input Capacitance
- Totally Lead-Free & Fully RoHS Compliant (Notes 1 & 2)
- Halogen and Antimony Free. "Green" Device (Note 3)

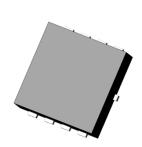
Description and Applications

This new generation MOSFET is designed to minimize the on-state resistance (R_{DS(ON)}) yet maintain superior switching performance, which makes it ideal for high-efficiency power management applications.

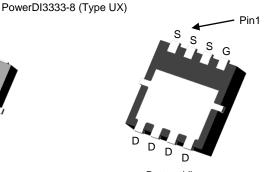
- Power Management Functions
- DC-DC Converters

Mechanical Data

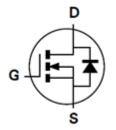
- Case: PowerDI[®]3333-8 (Type UX)
- Case Material: Molded Plastic, "Green" Molding Compound. UL Flammability Classification Rating 94V-0
- Moisture Sensitivity: Level 1 per J-STD-020
- Terminals: Finish—Matte Tin Annealed over Copper Leadframe. Solderable per MIL-STD-202, Method 208 @3
- Weight: 0.072 grams (Approximate)







Bottom View



Equivalent Circuit

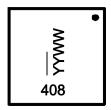
Ordering Information (Note 4)

Part Number	Case	Packaging
DMT4008LFV-7	PowerDI3333-8 (Type UX)	2000/Tape & Reel
DMT4008LFV-13	PowerDI3333-8 (Type UX)	3000/Tape & Reel

Notes:

- 1. No purposely added lead. Fully EU Directive 2002/95/EC (RoHS), 2011/65/EU (RoHS 2) & 2015/863/EU (RoHS 3) compliant.
- 2. See https://www.diodes.com/quality/lead-free/ for more information about Diodes Incorporated's definitions of Halogen- and Antimony-free, "Green" and
- 3. Halogen- and Antimony-free "Green" products are defined as those which contain < 900ppm bromine, < 900ppm chlorine (< 1500ppm total Br + CI) and <1000ppm antimony compounds.
- 4. For packaging details, see https://www.diodes.com/design/support/packaging/diodes-packaging/.

Marking Information



408 = Product Type Marking Code YYWW = Date Code Marking YY = Last Two Digits of Year (ex: 18 = 2018) WW = Week Code (01 to 53)



Characteristic	Symbol	Value	Unit	
Drain-Source Voltage	V_{DSS}	40	V	
Gate-Source Voltage		V_{GSS}	±20	V
Continuous Drain Current, V _{GS} = 10V (Note 6)	$T_C = +25$ °C $T_C = +70$ °C	I _D	54.8 43.9	А
Continuous Drain Current, $V_{GS} = 10V$ (Note 5) $T_A = +25^{\circ}C$ $T_A = +70^{\circ}C$		I _D	12.1 9.7	А
Pulsed Drain Current (10µs Pulse, Duty Cycle = 1%)	I _{DM}	70	Α	
Maximum Continuous Body Diode Forward Current (Note 6)	Is	29.8	Α	
Pulsed Body Diode Forward Current (10µs Pulse, Duty Cycle = 1%	I _{SM}	70	Α	
Avalanche Current, L = 0.3mH	I _{AS}	11.3	Α	
Avalanche Energy, L = 0.3mH	E _{AS}	19.2	mJ	

Thermal Characteristics (@T_A = +25°C, unless otherwise specified.)

Characteristic		Symbol	Value	Unit
Total Power Dissipation (Note 5)	$T_A = +25^{\circ}C$	P_{D}	1.9	W
Thermal Resistance, Junction to Ambient (Note 5)		R _{ÐJA}	64	°C/W
Total Power Dissipation (Note 6)	$T_C = +25^{\circ}C$	P_{D}	35.7	W
Thermal Resistance, Junction to Case (Note 6)		Rejc	3.5	°C/W
Operating and Storage Temperature Range		$T_{J_{i}}T_{STG}$	-55 to +150	°C

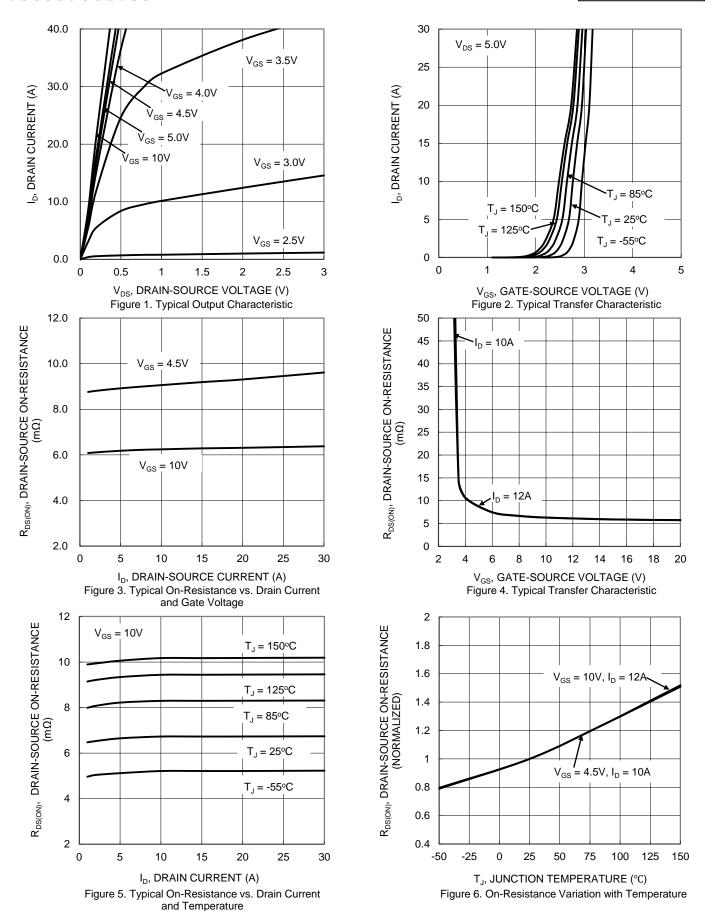
Electrical Characteristics (@T_A = +25°C, unless otherwise specified.)

Characteristic	Symbol	Min	Тур	Max	Unit	Test Condition	
OFF CHARACTERISTICS (Note 7)							
Drain-Source Breakdown Voltage	BV _{DSS}	40	_	_	V	$V_{GS} = 0V, I_D = 250\mu A$	
Zero Gate Voltage Drain Current	I _{DSS}		_	1	μΑ	$V_{DS} = 32V, V_{GS} = 0V$	
Gate-Source Leakage	I _{GSS}		_	±100	nA	$V_{GS} = \pm 20V, V_{DS} = 0V$	
ON CHARACTERISTICS (Note 7)						_	
Gate Threshold Voltage	V _{GS(TH)}	1	_	3	V	$V_{DS} = V_{GS}$, $I_D = 250\mu A$	
Static Drain-Source On-Resistance	D-s/s/	_	6.5	7.9	mΩ	$V_{GS} = 10V, I_D = 12A$	
Static Drain-Source On-Nesistance	R _{DS(ON)}		9.4	12		$V_{GS} = 4.5V, I_D = 10A$	
Diode Forward Voltage	V_{SD}		_	1.2	٧	$V_{GS} = 0V, I_S = 10A$	
DYNAMIC CHARACTERISTICS (Note 8)							
Input Capacitance	C _{iss}		1179	_	pF	.,	
Output Capacitance	Coss		384	_	pF	$V_{DS} = 20V, V_{GS} = 0V,$ - f = 1MHz	
Reverse Transfer Capacitance	C _{rss}		42	_	pF	1 – 1101112	
Gate Resistance	R_g	l	1.7		Ω	$V_{DS} = 0V$, $V_{GS} = 0V$, $f = 1MHz$	
Total Gate Charge (V _{GS} = 10V)	Q_g		17.1		nC		
Total Gate Charge (V _{GS} = 4.5V)	Q_g	l	8.3		nC	V _{DS} = 20V. I _D = 10A	
Gate-Source Charge	Qgs	_	2.4	_	nC	$V_{DS} = 20V$, $I_D = 10A$	
Gate-Drain Charge	Q_{gd}	_	3.4	_	nC	1	
Turn-On Delay Time	t _{D(ON)}		3.5	_	ns	$V_{DD} = 20V, V_{GS} = 10V,$ $R_G = 6\Omega, I_D = 10A$	
Turn-On Rise Time	t _R	_	3.7	_	ns		
Turn-Off Delay Time	t _{D(OFF)}		17.1	_	ns		
Turn-Off Fall Time	t _F		6.4	_	ns		
Body Diode Reverse Recovery Time	t _{RR}		19.8	_	ns	$I_F = 10A$, di/dt = 400A/ μ s	
Body Diode Reverse Recovery Charge	Q _{RR}	_	8.8	_	nC		

Notes:

- 5. Device mounted on FR-4 substrate PCB, 2oz copper, with thermal bias to bottom layer and 1inch square copper plate.
- 6. Thermal resistance from junction to soldering point (on the exposed drain pad).7. Short duration pulse test used to minimize self-heating effect.
- 8. Guaranteed by design. Not subject to product testing.







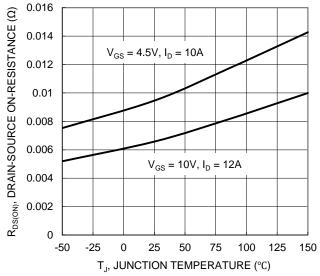
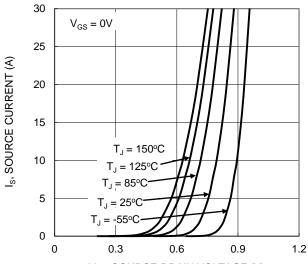


Figure 7. On-Resistance Variation with Temperature



V_{SD}, SOURCE-DRAIN VOLTAGE (V) Figure 9. Diode Forward Voltage vs. Current

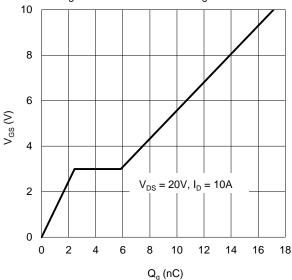
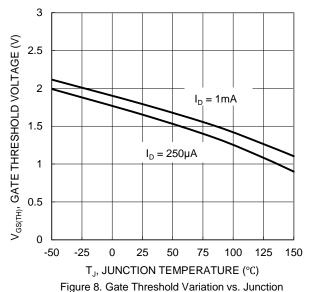
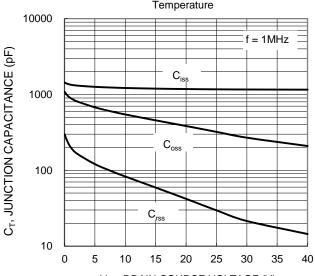


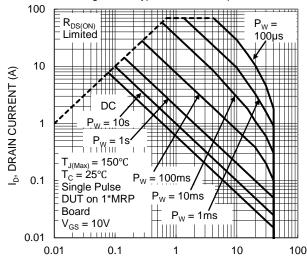
Figure 11. Gate Charge



Temperature



 $V_{\rm DS}$, DRAIN-SOURCE VOLTAGE (V) Figure 10. Typical Junction Capacitance



V_{DS}, DRAIN-SOURCE VOLTAGE (V) Figure 12. SOA, Safe Operation Area



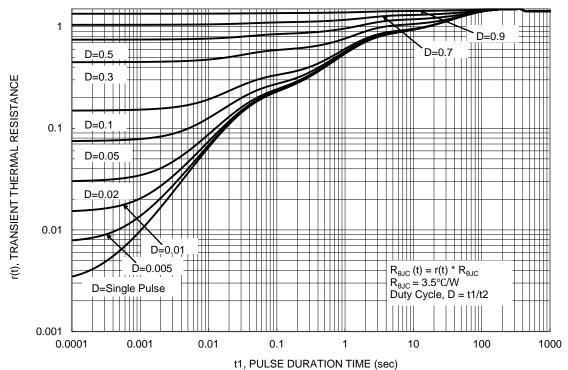


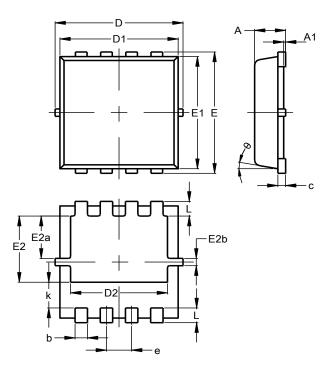
Figure 13. Transient Thermal Resistance



Package Outline Dimensions

Please see http://www.diodes.com/package-outlines.html for the latest version.

PowerDI3333-8 (Type UX)

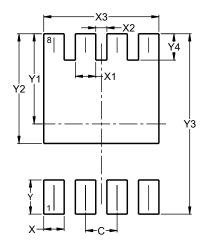


PowerDI3333-8 (Type UX)					
Dim	Min	Max	Тур		
Α	0.75	0.85	0.80		
A1	0.00	0.05	_		
b	0.25	0.40	0.32		
С	0.10	0.25	0.15		
D	3.20	3.40	3.30		
D1	2.95	3.15	3.05		
D2	2.30	2.70	2.50		
Е	3.20	3.40	3.30		
E1	2.95	3.15	3.05		
E2	1.60	2.00	1.80		
E2a	0.95	1.35	1.15		
E2b	0.10	0.30	0.20		
е	0.65 BSC				
k	0.50	0.90	0.70		
L	0.30	0.50	0.40		
θ	0°	12°	10°		
All Dimensions in mm					

Suggested Pad Layout

Please see http://www.diodes.com/package-outlines.html for the latest version.

PowerDI3333-8 (Type UX)



Dimensions	Value (in mm)		
С	0.650		
X	0.420		
X1	0.420		
X2	0.230		
Х3	2.370		
Y	0.700		
Y1	1.850		
Y2	2.250		
Y3	3.700		
Y4	0.540		



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